DS3658

DS3658 Quad High Current Peripheral Driver



Literature Number: SNLS365A



DS3658

Quad High Current Peripheral Driver

General Description

The DS3658 quad peripheral driver is designed for those applications where low operating power, high breakdown voltage, high output current and low output ON voltage are required. A unique input circuit combines TTL compatibility with high impedance. In fact, its extreme low input current allows it to be driven directly by a CMOS device.

The outputs are capable of sinking 600 mA each and offer a 70V breakdown. However, for inductive loads the output should be clamped to 35V or less to avoid latch-up during turn off (inductive fly back protection—refer AN-213). An on-chip clamp diode capable of handling 800 mA is provided at each output for this purpose. In addition, the DS3658 incorporates circuitry that guarantees glitch-free power up or down operation and a fail-safe feature which puts the output in a high impedance state when the input is open.

The molded package is specifically constructed to allow increased power dissipation over conventional packages. The four ground pins are directly connected to the device chip with a special cooper lead frame. When the quad driver is soldered into a PC board, the power rating of the device improves significantly.

Applications

- Relay drivers
- Lamp drivers
- Solenoid drivers
- Hammer drivers
- Stepping motor drivers

- Triac drivers
- LED drivers
- High current, high voltage drivers
- Level translators
- Fiber optic LED drivers

Features

- Single saturated transistor outputs
- Low standby power, 10 mW typical
- High impedance TTL compatible inputs
- Outputs may be tied together for increased current capacity
- High output current
- 600 mA per output
- 2.4A per package
- No output latch-up at 35V
- Low output ON voltage (350 mV typ @ 600 mA)
- High breakdown voltage (70V)
- Open collector outputs
- Output clamp diodes for inductive fly back protection
- NPN inputs for minimal input currents (1 µA typical)
- Low operating power
- Standard 5V power supply
- Power up/down protection
- Fail safe operation
- 2W power package
- Pin-for-pin compatible with SN75437

Connection Diagram

IN A IN B EN GND GND V_{CC} IN C IN D 16 15 14 13 12 11 10 9

Dual-In-Line Package

Top View Order Number DS3658N See NS Package Number N16E

GND

OUT C

CLAMP 2

00581901

GND

CLAMP 1

OUT B

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage 7V
Input Voltage 15V
Output Voltage 70V
Output Current 1.5A

Continuous Power Dissipation
@ 25°C Free-Air (Note 5)

2075 mW

Storage Temperature Range -65°C to $+150^{\circ}\text{C}$ Lead Temperature

260°C

Operating Conditions

(Soldering, 4 sec.)

	Min	Max	Units
Supply Voltage	4.75	5.25	V
Ambient Temperature	0	70	°C

Electrical Characteristics (Notes 2, 3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V _{IH}	Input High Voltage		2.0			V
V _{IL}	Input Low Voltage				0.8	V
I _{IH}	Input High Current	$V_{IN} = 5.25V, V_{CC} = 5.25V$		1.0	1.0	μA
I _{IL}	Input Low Current	$V_{IN} = 0.4V$			±10	μA
V _{IK}	Input Clamp Voltage	I ₁ = -12 mA		-0.8	-1.5	V
V _{OL}	Output Low Voltage	I _L = 300 mA		0.2	0.4	V
		I _L = 600 mA (Note 4)		0.35	0.7	V
I _{CEX}	Output Leakage Current	$V_{CE} = 70V, V_{IN} = 0.8V$			100	μA
V _F	Diode Forward Voltage	I _F = 800 mA		1.0	1.6	V
I _R	Diode Leakage Current	V _R = 70V			100	μA
I _{CC}	Supply Current	All Inputs High		60	85	mA
		All Inputs Low		2	4	mA

Switching Characteristics (Note 2)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{PHL}	Turn On Delay	$R_L = 60\Omega$, $V_L = 30V$		226	500	ns
t _{PLH}	Turn Off Delay	$R_L = 60\Omega$, $V_L = 30V$		2430	8000	ns

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The table of "Electrical Characteristics" provides conditions for actual device operation.

Note 2: Unless otherwise specified, min/max limits apply across the 0°C to +70°C temperature range and the 4.75V to 5.25V power supply range. All typical values are for $T_A = 25$ °C and $V_{CC} = 5.0$ V.

Note 3: All currents into device pins are shown as positive, all currents out of device pins are shown as negative, all voltages are referenced to ground, unless otherwise specified. All values shown as max or min are so classified on absolute value basis.

Note 4: All sections of this quad circuit may conduct rated current simultaneously, however, power dissipation averaged over a short interval of time must fall within specified continuous dissipation ratings.

Note 5: For operation over 25° free-air temperature, derate linearly to 1328 mW @ 70°C @ the rate of 16.6 mW/°C.

Truth Table

IN	EN	OUT
Н	Н	L
L	Н	Z
Н	L	Z
L	L	Z

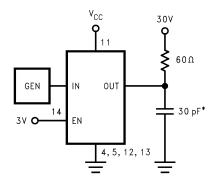
H = High state

L = Low state

Z = High impedance state

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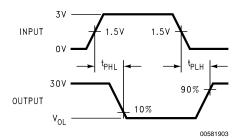
AC Test Circuit



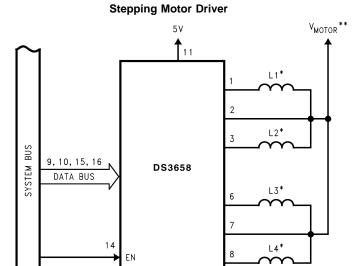
^{*}Includes probe and jig capacitance.

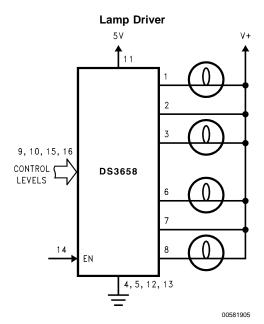
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Switching Waveforms



Typical Applications





 * L1, L2, L3, L4 are the windings of a bifilar stepping motor.

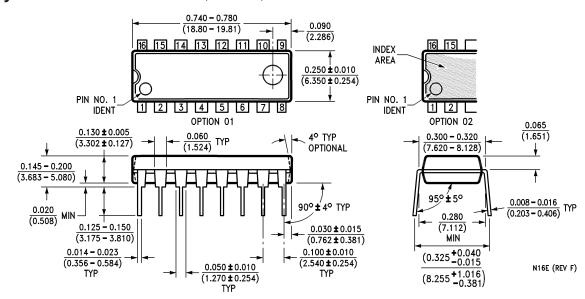
4, 5, 12, 13

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 $[\]ensuremath{^{**}}\ensuremath{V_{\text{MOTOR}}}$ is the supply voltage of the motor.

Physical Dimensions inches (millimeters) unless otherwise noted



Molded Dual-In-Line Package (N) Order Number DS3658N NS Package Number N16E

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